

PCN Number:	20190329000.1			PCN Date:	Mar 29 2019						
Title:	Qualification of TIPI as an additional Assembly and Test site for selected devices										
Customer Contact:	PCN Manager	Dept:	Quality Services								
Proposed 1st Ship Date:	Jun 29 2019	Estimated Sample Availability:	Date provided at sample request								
Change Type:											
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site						
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials						
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process						
PCN Details											
Description of Change:											
Texas Instruments is pleased to announce the qualification of TI Philippines (TIPI) as an Additional Assembly and test site for the list of devices shown below. Current material differences are as follows.											
<table border="1"> <thead> <tr> <th></th> <th>JCET</th> <th>TIPI</th> </tr> </thead> <tbody> <tr> <td>Mold compound</td> <td>S#120800005407</td> <td>4222198</td> </tr> </tbody> </table>							JCET	TIPI	Mold compound	S#120800005407	4222198
	JCET	TIPI									
Mold compound	S#120800005407	4222198									
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.											
Reason for Change:											
Continuity of Supply											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Anticipated impact on Material Declaration											
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp								
Changes to product identification resulting from this PCN:											
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City								
JCET	JCE	CHN	Jiangyin								
TIPI	PHI	PHL	Baguio City								
Sample product shipping label (not actual product label)											



MADE IN: Malaysia
2DC: 20:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM:
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLV62568PDDCR	TLV62568PDDCT	TLV62569PDDCR	TLV62569PDDCT
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**TI Information
Selective Disclosure**

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV62568PDDCR	Qual Device: TLV62569PDDCR	QBS Product Reference: TLV62568DBV	QBS Product Reference: TLV62569DBV
AC	Autoclave 121C	96 Hours	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	1/1000/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-
HBM	ESD - HBM	2500 V	-	-	1/3/0	-
CDM	ESD - CDM	1500 V	-	-	1/3/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	1/77/0	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-
LU	Latch-up	(per JESD78)	-	-	1/6/0	2/12/0
SD	Surface Mount Solderability	Pb Free	-	-	-	-
SD	Surface Mount Solderability	Pb	-	-	-	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	1/77/0	-	1/77/0

Type	Test Name / Condition	Duration	QBS Product Reference: TLV62569PDDC	QBS Package Reference: TLV62568DRL	QBS Package Reference: TLV62569DRLR
AC	Autoclave 121C	96 Hours	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
HBM	ESD - HBM	2500 V	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	-	-
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	-
LU	Latch-up	(per JESD78)	1/6/0	-	-
SD	Surface Mount Solderability	Pb Free	-	3/66/0	-
SD	Surface Mount Solderability	Pb	-	3/66/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	1/77/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com